

PROCEEDINGS OF SPIE

# ***Metrology, Inspection, and Process Control for Microlithography XXXII***

**Vladimir A. Ukraintsev**  
**Ofer Adan**  
*Editors*

**26 February–1 March 2018**  
**San Jose, California, United States**

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*Published by*  
SPIE

**Volume 10585**

Proceedings of SPIE 0277-786X, V. 10585

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Metrology, Inspection, and Process Control for Microlithography XXXII, edited  
by Vladimir A. Ukraintsev, Ofer Adan, Proc. of SPIE Vol. 10585, 1058501  
© 2018 SPIE · CCC code: 0277-786X/18/\$18 · doi: 10.1117/12.2323955

Proc. of SPIE Vol. 10585 1058501-1

The papers in this volume were part of the technical conference cited on the cover and title page. Papers were selected and subject to review by the editors and conference program committee. Some conference presentations may not be available for publication. Additional papers and presentation recordings may be available online in the SPIE Digital Library at [SPIDigitalLibrary.org](http://SPIDigitalLibrary.org).

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Please use the following format to cite material from these proceedings:

Author(s), "Title of Paper," in *Metrology, Inspection, and Process Control for Microlithography XXXII*, edited by Vladimir A. Ukraintsev, Ofer Adan, Proceedings of SPIE Vol. 10585 (SPIE, Bellingham, WA, 2018) Seven-digit Article CID Number.

ISSN: 0277-786X  
ISSN: 1996-756X (electronic)

ISBN: 9781510616622  
ISBN: 9781510616639 (electronic)

Published by

**SPIE**

P.O. Box 10, Bellingham, Washington 98227-0010 USA  
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

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